

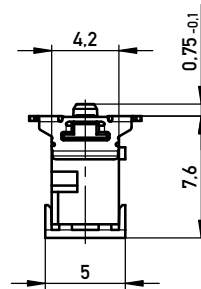
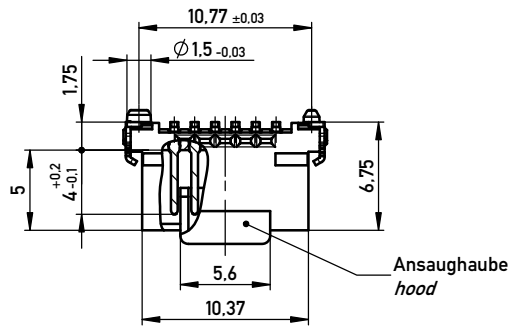
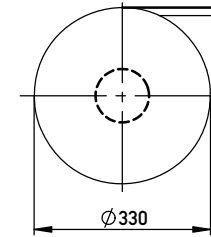
Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

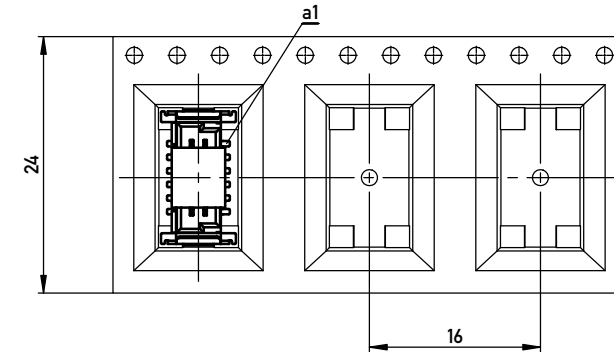
Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0,1 mm

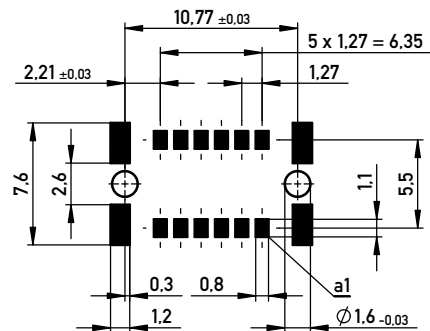
Verpackt im Gurt nach DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 280 Stück
Packaging unit: 280 pcs



Abspulrichtung - Reel off Direction



Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



BA 8-13 - 8mm Bauhöhe
type 8-13 - Low Profile

| | | | | |
|---|--|--------------------------|---|-----|
| Information: | Tolerances | All Dimensions in mm | Scale | 3:1 |
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| Subject to modification without prior notice. Drawing will not be updated. | | www.ERNI.com | 244836 | |
| e | 30.06.2015 | | Class SMCQ | |
| Index | Date | I A3 | | |

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